Amendments to the Specification

On page 7, please delete paragraph 4 and replace with the following:

The first and second circuit conductors 1001, 1002 can be formed as conductive vias, for example, by laser or mechanical drilling through the printed wiring board ~~1100~~ 1000. The holes formed by drilling are then plated with a conductive material. The resulting conductive vias 1001, 1002, which extend through the entire printed wiring board 1000 shown in FIG. 1A, are typically referred to as "plated through-holes." Plated through-hole type vias are usually formed after all of the innerlayer panels of a printed wiring board have been laminated together. Additional circuit conductors (not shown) in other parts of the printed wiring board 1000 could extend through subassemblies of innerlayer panels or through individual innerlayer panels. Via circuit conductors extending through only a part of the printed wiring board 1000 are commonly referred to as "buried vias." Buried vias are typically drilled and plated through a subassembly of innerlayer panels before the subassembly of innerlayer panels is incorporated into a printed wiring board. A small diameter conductive via formed on one or both sides of an innerlayer panel is commonly referred to as a "microvia," and may be used, for example, to terminate a capacitor within an innerlayer panel. Any of the above-mentioned types of vias may be connected to the innerlayer panel embodiments discussed in this specification.

On page 18, please delete the second full paragraph and replace with the following:

FIG. 8D is a top plan view of a next stage of manufacture. FIG. 8E is a section view taken on line 8E-8E in FIG. 8D. Referring to FIG. 8D, a photo-resist is applied to the first foil 32, and the foil 32 is imaged, etched and stripped. The electrodes 810, ~~812~~ 820, including the first and second elongated electrode portions 812, ~~814~~ 822, the serpentine trench 828, and the conductive portions 814, 824 result from the etching step. The second foil 34 may also be etched to form circuitry 8010. The circuitry 8010 illustrated in FIG. 8E can act as, for example, a power plane 8010 in the finished printed wiring board 8000 (illustrated in FIG. 8J).

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